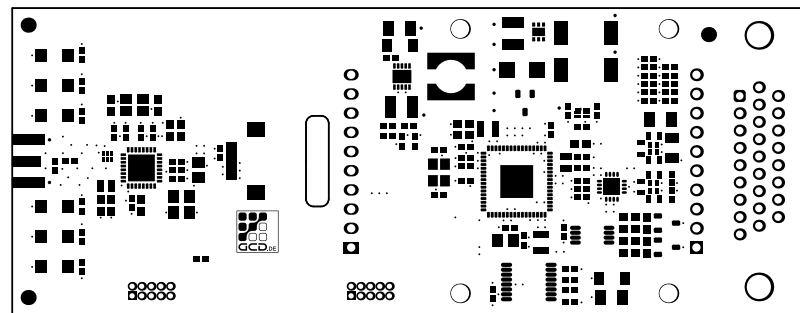
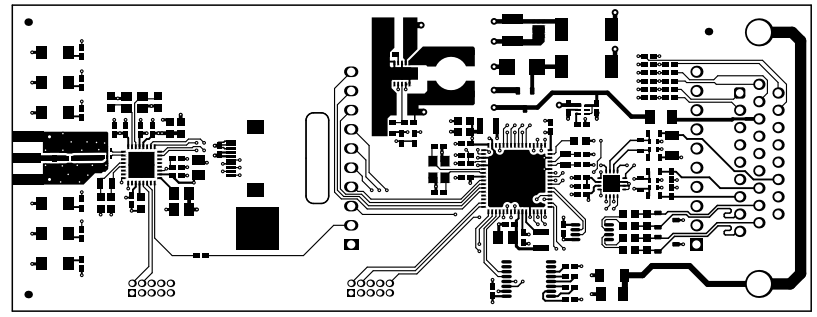


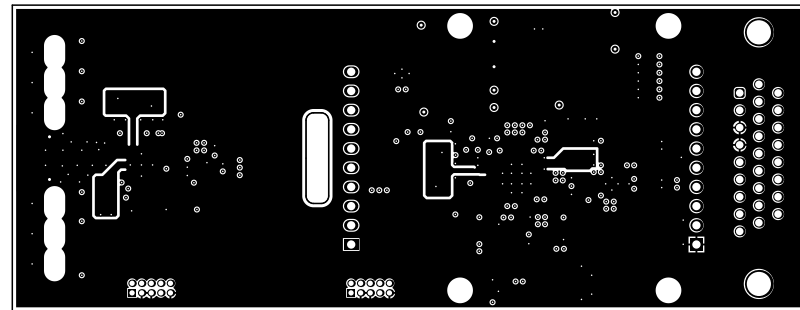
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01439		
PLOT NAME = Top Overlay	GENERATED : 11/14/2017 4:16:53 PM	TEXAS INSTRUMENTS	



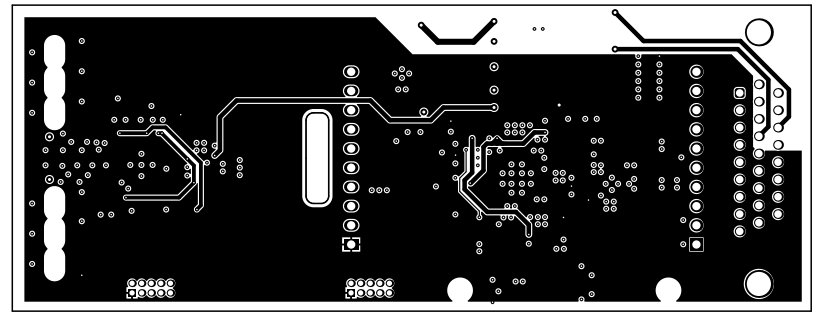
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01439		
PLOT NAME = Top Solder Mask	GENERATED : 11/14/2017 4:16:55 PM	TEXAS INSTRUMENTS	



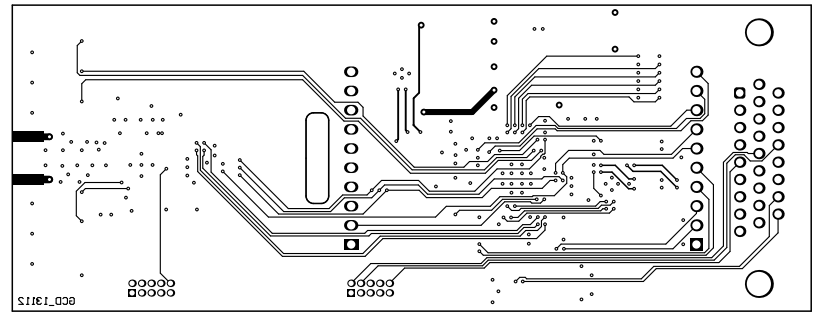
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01439		
PLOT NAME = Top Layer	GENERATED : 11/14/2017 4:16:56 PM	TEXAS INSTRUMENTS	



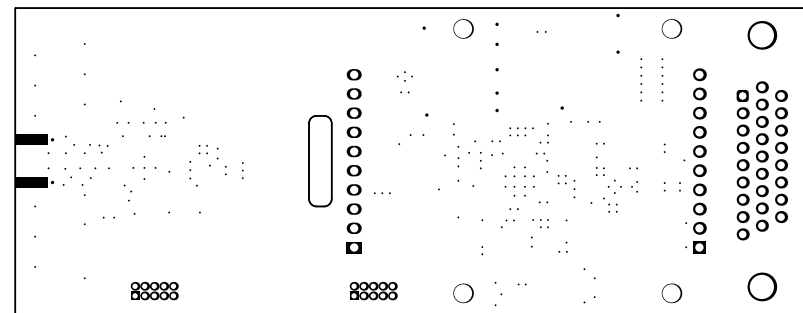
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01439		
PLOT NAME = Signal Layer 1	GENERATED : 11/14/2017 4:16:57 PM	TEXAS INSTRUMENTS	



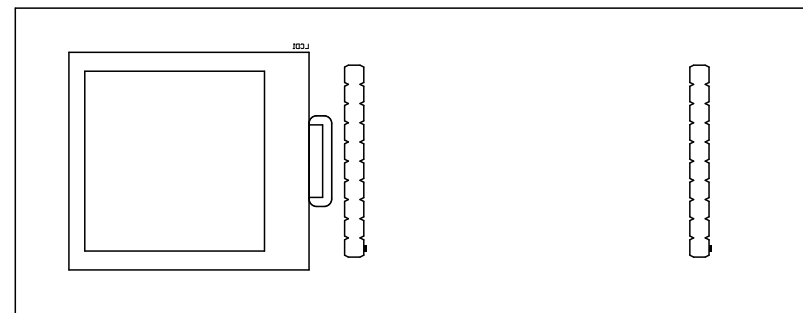
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01439		
PLOT NAME = Signal Layer 2	GENERATED : 11/14/2017 4:16:58 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: TIDA-01439		
PLOT NAME = Bottom Layer	GENERATED : 11/14/2017 4:16:59 PM	TEXAS INSTRUMENTS	



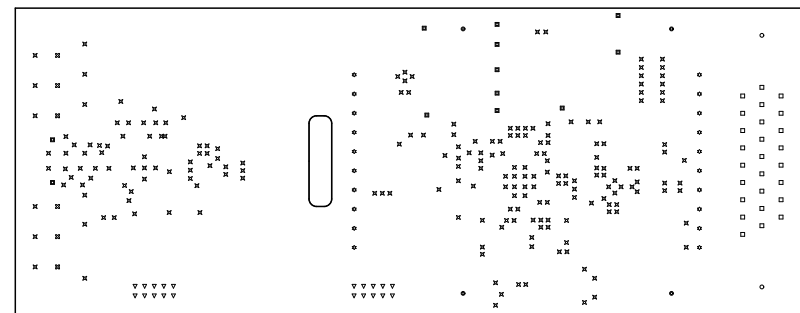
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01439		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/14/2017 4:17:01 PM	TEXAS INSTRUMENTS	



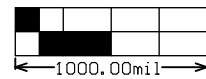
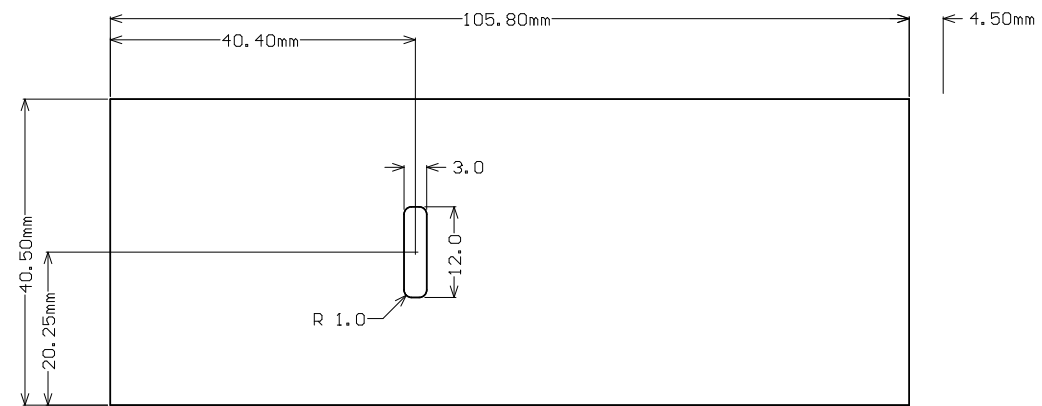
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01439		
PLOT NAME = Bottom Overlay	GENERATED : 11/14/2017 4:17:02 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair
⊠	215	0.200mm (7.87mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
⊞	12	0.400mm (15.75mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
▽	20	0.700mm (27.56mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
□	26	1.000mm (39.37mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
⊛	20	1.100mm (43.31mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
⊗	6	1.800mm (70.87mil)	NPTH	Slot	Layer 1 - Top Layer - Layer 4 - Bottom Layer
⊙	4	2.400mm (94.49mil)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
○	2	3.200mm (125.98mil)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer
	305 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01439		
PLOT NAME = Drill Drawing	GENERATED : 11/14/2017 4:17:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01439		
PLOT NAME = Board Dimensions	GENERATED : 11/14/2017 4:17:05 PM		TEXAS INSTRUMENTS

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